MITSUI
KINZOKU

MLS-G

- MLS-G 銅箔係於表面處理製程反轉處理銅箔, 其一般特性和 HTE(STD)銅箔無差異,
  具有良好的線路可靠性,適用於內層之細線路及多層增層板用。
- MLS-G has passed through reverse side treatment process. It has the same general properties as HTE(STD) foils with better pattern reliability, ensuring good performance in fine line patterning for inner and build-up layers.

- 具較低的稜線為應用於高速訊號傳輸板最佳銅箔材料.

  Very low profile of MLS-G makes it an excellent material to apply to high speed transmission board.

用途/Application

- **適用於多層印刷電路板(HDI)**
  /High Density Interconect(HDI)
- **高速訊號傳輸板**
  /HSD (High speed digital)
- **基地台/伺服器**
  /Base station / Server

結構/Composition

生產地點/Production Site

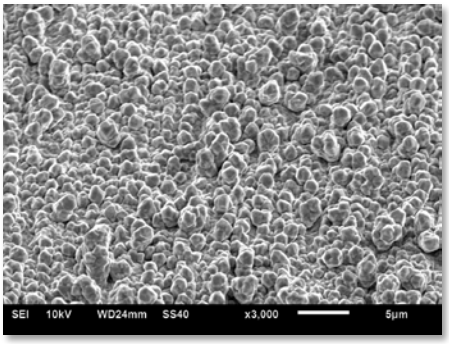
- **台灣 / Taiwan**
- **馬來西亞 / Malaysia**

特性代表值/Representative data

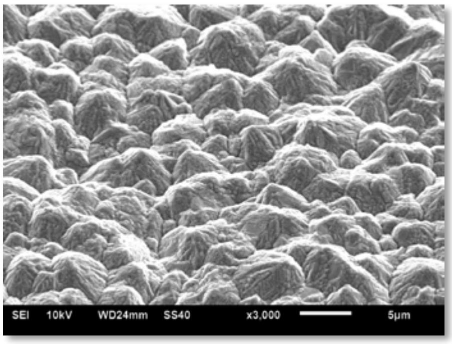
	μ m	Rz (μ m)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
MLS-G	12	3.0	370	6	0.9
	18	3.0	370	8	1.0
	35	3.0	370	16	1.3
	70	3.0	370	19	1.5

※上述表列為代表性數據非保証值。
This is representative data, not guarantee.

處理面/Laminate side



阻劑面/ Resist side



MLS-G *STD. type heavy foil series*

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- 適用於較高電流設計板材之符合新一代環保要求之電解銅箔.

  MLS-G heavy copper foil comply with environment regulation is suitable for use in high current board design.
- 處理面極低粗度特性極適用於薄板.

  Bonding side with very low roughness is excellent to apply to thin core laminate.
- 銅箔穩定的量產能力, 可充分供應客戶需求.

  Our plant has stable capacity for MLS-G to fulfill customer requirements.

用途/Application

- **汽車板**
  /Automotive board
- **與電源供應器**
  /Power supply unit
- **基地台板**
  /Base station

結構/Composition

生產地點/Production Site

- **台灣** / Taiwan

特性代表值/Representative data

	μm	Rz (μm)	Tensile Strength (N/mm2)	Elogation (%)	Peel Strength (kg/cm)
MLS-G	105	3.0	300	15	2.0
	140	3.0	300	15	2.1
	175	3.0	300	15	2.2
	210	3.0	300	15	2.4

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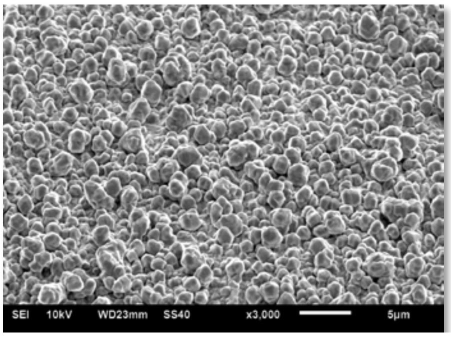
處理面/Laminate side



阻劑面/ Resist side